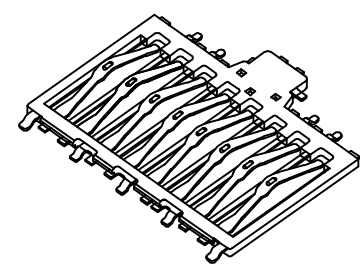
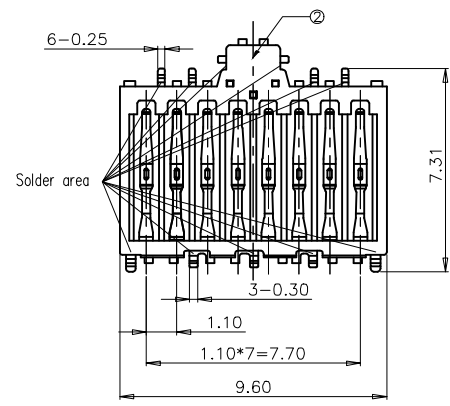
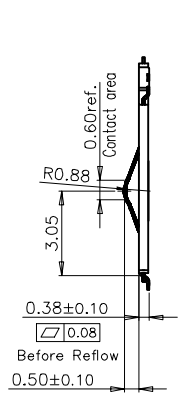
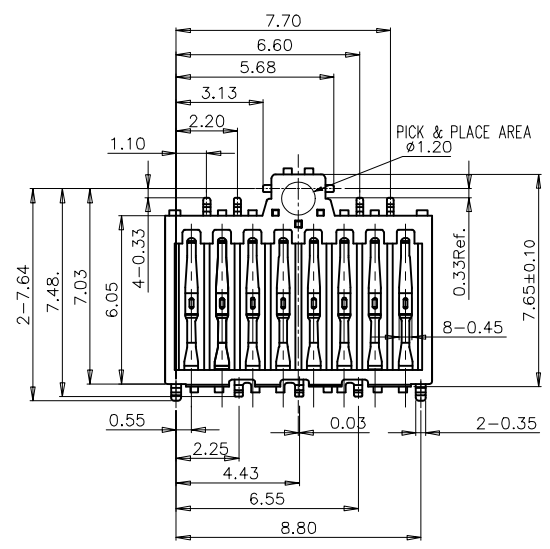


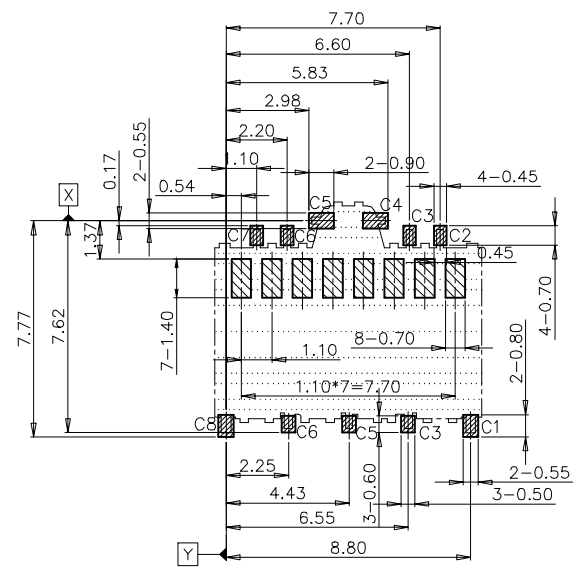
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2015/10/31



μSD Block Pin Definition

PIN	NAME
C1	DATA2
C2	CD/DATA3
C3	CMD
C4	VCD
C5	CLK
C6	Vss2
C7	DATA0
C8	DATA1

- NOTES:
- MATERIAL:SEE TABLE 1.
 - SPECIALITY:
 - Rated current:0.5A Max
 - Rated voltage:10V DC
 - Contact Resistance:60mΩ MAX
 - Insulation Resistance:1000MΩ MIN 500V DC
 - Dielectric withstanding voltage: 500V AC 1 MINUTE.
 - Solder ability:245±5℃, 5±0.5s.
 - Durability:3000 Cycles Min.
 - Operating condition:Temperature-20℃~+85℃, Humidity 80% R.H MAX
 - MECHANICAL:
 - Contact Force:0.2N Min
 - PLEASE CONTACT KRCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY



- Soldering Pad area
- Open wire restricted area (possibly touch of componets on PCB)
- Connector outline
- Pad area(only for mechanical function)
 - Touch area of contact tips, no electrical function and only for mechanical function
 - Don't brush Tin pasted on the area during SMT process.

RECOMMEND PCB LAYOUT (TOLERANCE ±0.05)

②	Housing	1	LCP	COLOUR:BLACK	UL 94V-0
①	Contact	1	COPPER ALLOY	Contact Area: Au 3U"Min, Solder area: Au 1U"Min ;Under plate Ni 50u"Min all over	T=0.08±0.01mm
NO.	PART NAME	QTY	MATERIAL	DESCRIPTION	REMARK

GENERAL TOLERANCE		DWG NO.	JYSA0909-001	APPD:	WIND	Scale	1:1
X±0.45	x:±5°	Title	0.3H Micro SD CARD CONN.	CHKD:		UNIT	mm
.X±0.35	.x:±2°			DR:			
.XX±0.25	.xx:±1°	Part NO.	JYS-TF030-060	Date	2015/10/31		
.XXX±0.15	.xxx:±0.5°			JYSCONN Shenzhen			
SHEET	1/1	JYSCONN Electronics Co., LTD.					